



CC2541 Postage Stamp Reference Design - Bill of Materials

Item Number	Value	Quantity	Part Number	MPN	Description	Part Reference	Manufacturer	Datasheet URL 1
1	2450AT42A100	1	13-00494	2450AT42A100E	MECHANIC, ANTENNA, HIGH FREQUENCY CERAMIC, 50R, 2.4GHz-2.5GHz, SMD	A1	JOHANSON TECHNOLOGY	
2	2.2uF	1	02-04476	GRM155R60J225KE95D	CAPACITOR, CERAMIC X5R, 2.2uF, 6.3V, -10%/+10%, -55DEGC/+85DEGC, 0402, SMD	C1	MURATA	http://search.murata.co.jp/Ceramy/image/img/A01X/G101/ENG/GRM155R60J225KE95-
3	100nF	5	02-01686	02016D104KAT2A	CAPACITOR, CERAMIC X5R, 100nF, 6.3V, -10%/+10%, -55DEGC/+85DEGC, 0201, SMD	C101 C211 C241 C271 C311	AVX	N/A
4	1000pF	1	02-00593	GRM033R71C102KD01D	CAPACITOR, CERAMIC, 1000pF, 10pF, X7R, 16V, 0201, SMD	C201	MURATA	http://www.murata.com/products/catalog/pdf/c02e.pdf
5	12pF	2	02-04277	02013A120JAT2A	CAPACITOR, CERAMIC COG/NP0, 12pF, 25V, -5%/+5%, -55DEGC/+125DEGC, 0201, SMD	C221 C231	AVX	N/A
6	DNM	2	02-01320		CAPACITOR, DO NOT MOUNT, 0201, SMD	C251 C252		
7	220pF	1	02-04294	0201YC221KAT2A	CAPACITOR, CERAMIC X7R, 220pF, 16V, -10%/+10%, -55DEGC/+125DEGC, 0201, SMD	C272	AVX	N/A
8	15pF	2	02-04278	02013A150JAT2A	CAPACITOR, CERAMIC COG/NP0, 15pF, 25V, -5%/+5%, -55DEGC/+125DEGC, 0201, SMD	C321 C331	AVX	N/A
9	1uF	2	02-00564	GRM155F50J105ZE01D	CAPACITOR, CERAMIC, 1uF, -20%+80%, Y5V, 6.3V, 0402, SMD	C391 C401	MURATA	http://search.murata.co.jp/Ceramy/image/img/A01X/G101/ENG/GRM155F50J105ZE01-
10	2450BM15A0002	1	04-00532	2450BM15A0002E	FILTER, FILTER BALUN, 2400MHZ TO 2500MHZ, -40DEGC/+125DEGC, 0805, SMD	FL1	JOHANSON TECHNOLOGY	
11	BLM15HG102SN1	1	04-00032	BLM15HG102SN1D	FILTER, INDUCTOR TYPE, 1000OHM@100MHZ, 25%,250mA, 0402, SMD	L1	MURATA	http://search.murata.co.jp/Ceramy/image/img/PDF/ENG/L0110S0101BLM15H.pdf
12	2.7k	1	01-04074	CRCW02012K70FKED	RESISTOR, THICK FILM, 2K7, -1%/+1%, 0.05W, 30V, -55DEGC/+125DEGC, 0201, SMD	R201	VISHAY DALE	http://www.vishay.com/docs/20035/dcrwe3.pdf
13	0	1	01-04043	CRCW02010000Z0ED	RESISTOR, THICK FILM, 0R, -55DEGC/+125DEGC, 0201, SMD	R251	VISHAY	
14	56k	1	01-04100	CRCW020156K0FKED	RESISTOR, THICK FILM, 56K, -1%/+1%, 0.05W, 30V, -55DEGC/+125DEGC, 0201, SMD	R301	VISHAY DALE	http://www.vishay.com/docs/20035/dcrwe3.pdf
15	TP_0.5MM_PTH	14	19-00199		TESTPOINT, 0.5MM HOLE, PTH	TP2 TP3 TP9 TP11 TP14 TP15 TP16 TP17		
16	CC2541F256	1	18-28143	CC2541F256RHAR	IC, DIGITAL WIRELESS, 2.4-GHz BLUETOOTH® LOW ENERGY AND PROPRIETARY SYSTEM-ON-CHIP, 256 KB, 2V TO 3.6V, VQFN40, SMD	U1	TEXAS INSTRUMENTS	N/A
17	32MHz	1	12-00422	FA-128 32MHz 10pF 10PPM	CRYSTAL, OSCILATOR, 32MHz, 10pF, -10PPM/+10PPM, -40DEGC/+85DEGC, SMD	X1	Epson Toyocom	http://www.epsontoyocom.co.jp/english/product/Crystal/set02/fa128/index.html
18	32.768kHz	1	12-00430	FC-12M 32.7680KA-A3	CRYSTAL, OSCILATOR, 32.768kHz, -20PPM/ +20PPM, -40DEGC/ +85DEGC, 12.5pF, SMD	X2	EPSON	http://www.eea.epson.com/portal/pls/portal/docs/1/1525528.PDF

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